L Number	Hits	Search Text	DB	Time stamp
1	1560	(438/455-459).CCLS.	USPAT; US-PGPUB	2004/03/21 06:38
2	523095	mold$3	USPAT; US-PGPUB	2004/03/21 06:39
3	137	((438/455-459).CCLS.) and mold$3	USPAT; US-PGPUB	2004/03/21 06:47
4	1146	mold$3 and 216/$.ccls.	USPAT; US-PGPUB	2004/03/21 07:10
5	111	((mask$3 and mold$3 and (etch$3 with (wafer substrate))) and (mold$3 with (metal conductive))) and 216/$.ccls.	USPAT; US-PGPUB	2004/03/21 06:48
6	600290	carrier	USPAT; US-PGPUB	2004/03/21 06:48
7	257	(mold$3 and 216/$.ccls.) and carrier	USPAT; US-PGPUB	2004/03/21 06:49
8	233	((mold$3 and 216/$.ccls.) and carrier) not (((mask$3 and mold$3 and (etch$3 with (wafer substrate))) and (mold$3 with (metal conductive))) and 216/$.ccls.)	USPAT; US-PGPUB	2004/03/21 06:55
9	152753	wafer	USPAT; US-PGPUB	2004/03/21 06:55
10	376	(mold$3 and 216/$.ccls.) and wafer	USPAT; US-PGPUB	2004/03/21 06:55
11	195	((mold$3 and 216/$.ccls.) and wafer) not (((mold$3 and 216/$.ccls.) and carrier) not (((mask$3 and mold$3 and (etch$3 with (wafer substrate))) and (mold$3 with (metal conductive))) and 216/$.ccls.)) not ((mold$3 and 216/$.ccls.) and carrier) not (((mask$3 and mold$3 and (etch$3 with (wafer substrate))) and (mold$3 with (metal conductive))) and 216/$.ccls.)	USPAT; US-PGPUB	2004/03/21 07:02
13	100827	etch$3 with (wafer substrate)	USPAT; US-PGPUB	2004/03/21 07:01
14	4515	(mold$3 and wafer) and (etch$3 with (wafer substrate))	USPAT; US-PGPUB	2004/03/21 07:02
15	1674	carrier and ((mold$3 and wafer) and (etch$3 with (wafer substrate)))	USPAT; US-PGPUB	2004/03/21 07:02
16	1561	(carrier and ((mold$3 and wafer) and (etch$3 with (wafer substrate)))) not (((mold$3 and 216/$.ccls.) and wafer) not (((mold$3 and 216/$.ccls.) and carrier) not (((mask$3 and mold$3 and (etch$3 with (wafer substrate))) and (mold$3 with (metal conductive))) and 216/$.ccls.)) not ((mold$3 and 216/$.ccls.) and carrier) not (((mask$3 and mold$3 and (etch$3 with (wafer substrate))) and (mold$3 with (metal conductive))) and 216/$.ccls.)) not ((mold$3 and 216/$.ccls.) and wafer) not (((mold$3 and 216/$.ccls.) and carrier) not (((mask$3 and mold$3 and (etch$3 with (wafer substrate))) and (mold$3 with (metal conductive))) and 216/$.ccls.)) not ((mold$3 and 216/$.ccls.) and carrier) not (((mask$3 and mold$3 and (etch$3 with (wafer substrate))) and (mold$3 with (metal conductive))) and 216/$.ccls.)	USPAT; US-PGPUB	2004/03/21 07:02
17	230	((mask$3 and mold$3 and (etch$3 with (wafer substrate))) and (mold$3 with (metal conductive))) and 438/$.ccls.	USPAT; US-PGPUB	2004/03/21 07:03
18	1519	((carrier and ((mold$3 and wafer) and (etch$3 with (wafer substrate)))) not (((mold$3 and 216/$.ccls.) and wafer) not (((mold$3 and 216/$.ccls.) and carrier) not (((mask$3 and mold$3 and (etch$3 with (wafer substrate))) and (mold$3 with (metal conductive))) and 216/$.ccls.)) not ((mold$3 and 216/$.ccls.) and carrier) not (((mask$3 and mold$3 and (etch$3 with (wafer substrate))) and (mold$3 with (metal conductive))) and 216/$.ccls.)) not ((mold$3 and 216/$.ccls.) and wafer) not (((mold$3 and 216/$.ccls.) and carrier) not (((mask$3 and mold$3 and (etch$3 with (wafer substrate))) and (mold$3 with (metal conductive))) and 216/$.ccls.)) not ((mold$3 and 216/$.ccls.) and carrier) not (((mask$3 and mold$3 and (etch$3 with (wafer substrate))) and (mold$3 with (metal conductive))) and 216/$.ccls.)) not (((mask$3 and mold$3 and (etch$3 with (wafer substrate))) and (mold$3 with (metal conductive))) and 438/$.ccls.)	USPAT; US-PGPUB	2004/03/21 07:04
19	889	(mold$3 and 216/$.ccls.) not ((mold$3 and 216/$.ccls.) and carrier)	USPAT; US-PGPUB	2004/03/21 07:10